

CLAIM AMENDMENTS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended). A test system for conducting a function test of a semiconductor element on a wafer, the semiconductor element having terminal pads, the test system comprising:

a voltage source delivering an output voltage and providing a supply voltage of the element being tested;

a pin card having:

a pin card board;

supply contact pins arranged on said pin card board
including one of said supply contact pins and another one
of said supply contact pins;

a resistance disposed on said pin card board; and

a read contact pin disposed on said pin card board and
connected to said one of said supply contact pins through

said resistance ~~producing a high impedance electrical~~
~~read connection to a terminal pad of the element being~~
tested;

said one of said supply contact pins and said read contact pin
being configured to contact one of said terminal pads of the
element being tested;

said other one of said supply contact pins being configured to
contact another one of said terminal pads of the element being
tested;

said read contact pin producing a high-impedance electrical
read connection to said one of said terminal pads of the
element being tested;

said one of said supply contact pins and said other one of
said ~~including two~~ supply contact pins each connected to the
voltage source for applying the supply voltage to the said one
of said terminal pads and said other one of said terminal pads
of the semiconductor element being tested; and

a regulator controlling the output voltage based upon an
electrical potential of said read contact pin.

Claim 2 (withdrawn). The test system according to claim 1,
wherein:

said pin card has a second read contact pin producing a high-impedance electrical read connection to another of the terminal pads of the element being tested; and

said regulator controlling the output voltage based upon an electrical potential of said read contact pin and an electrical potential of said second read contact pin.

Claim 3 (withdrawn). The test system according to claim 2, including a second resistance, said second read contact pin connected to another of said supply contact pins through said second resistance.

Claim 4 (currently amended). A test system for conducting a function test of a semiconductor element on a wafer, the semiconductor element having terminal pads, the test system comprising:

a voltage source delivering an output voltage and providing a supply voltage of the element being tested;

a pin card having:

a pin card board;

supply contact pins arranged on said pin card board
including one of said supply contact pins and another one
of said supply contact pins;

a resistance disposed on said pin card board; and

a read contact pin disposed on said pin card board and
connected to said one of said supply contact pins through
said resistance producing a high-impedance electrical
read connection to a terminal pad of the element being
tested;

said one of said supply contact pins and said read contact pin
being configured to contact one of said terminal pads of the
element being tested;

said other one of said supply contact pins being configured to
contact another one of said terminal pads of the element being
tested;

said read contact pin producing a high-impedance electrical
read connection to said one of said terminal pads of the
element being tested;

said one of said supply contact pins and said other one of
said ~~including two~~ supply contact pins each connected to the
voltage source for applying the supply voltage to ~~the~~ said one
of said terminal pads and said other one of said terminal pads
of ~~the~~ said element being tested; and

means for regulating the output voltage based upon an
electrical potential of said read contact pin.

Claim 5 (withdrawn). The test system according to claim 4,
wherein:

said pin card has a second read contact pin producing a high-
impedance electrical read connection to another of the
terminal pads of the element being tested; and

said regulating means regulates the output voltage based upon
an electrical potential of said read contact pin and an
electrical potential of said second read contact pin.

Claim 6 (withdrawn). The test system according to claim 5,
including a second resistance, said second read contact pin
connected to another of said supply contact pins through said
second resistance.

Claim 7 (withdrawn). A method for conducting, with a test system, a function test of a semiconductor element on a wafer, which comprises:

defining a desired supply voltage of the semiconductor element;

applying a supply voltage from a voltage source through two supply contact pins of a pin card to corresponding terminal pads of the element being tested;

producing a high-impedance electrical read connection to a terminal pad of the element being tested by connecting a supply contact pin to a read contact pin of the pin card through a resistance;

determining a potential of the read contact pin relative to a reference potential; and

regulating an output voltage of the voltage source dependent upon the determined potential of the read contact pin to achieve an approximation of the desired supply voltage.

Claim 8 (withdrawn). A method for conducting, with a test system, a function test of a semiconductor element on a wafer, which comprises:

defining a desired supply voltage of the semiconductor element;

applying a supply voltage from a voltage source through two supply contact pins of a pin card to corresponding terminal pads of the element being tested;

producing a high-impedance electrical read connection to terminal pads of the element being tested by respectively connecting first and second supply contact pins to first and second read contact pins of the pin card through a respective resistance;

determining a potential of the first and second read contact pins relative to a reference potential; and

regulating the output voltage of the voltage source dependent upon the determined potentials to achieve an approximation of the desired supply voltage.